

RELIABILITY REPORT  
FOR  
MAX837EUS  
PLASTIC ENCAPSULATED DEVICES

November 11, 2001

MAXIM INTEGRATED PRODUCTS  
120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

Written by



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## Conclusion

The MAX837 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX837 micropower voltage monitor contains a 1.204V precision bandgap reference and a comparator in a SOT143 package. The MAX837 has a push-pull output driver. Two external resistors set the trip threshold voltage.

#### B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
IN, OUT to GND	-0.3V to ( $V_{CC} + 0.3V$ )
Input Current	
$V_{CC}$	20mA
IN	10mA
Output Current, OUT	20mA
Rate of Rise, $V_{CC}$	100V/ $\mu$ s
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Lead Temp. (10 sec.)	+300°C
Power Dissipation	
4-Lead SOT143	320mW
Derates above +70°C	
4-Lead SOT143	4.00mW/°C

## II. Manufacturing Information

A. Description/Function:	4-Pin Micropower Voltage Monitor
B. Process:	S3 (Standard 3 micron silicon gate CMOS)
C. Number of Device Transistors:	54
D. Fabrication Location:	California or Oregon, USA
E. Assembly Location:	Malaysia or Thailand
F. Date of Initial Production:	November, 1996

## III. Packaging Information

A. Package Type:	4 Lead SOT-143
B. Lead Frame:	Alloy 42 or Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	Buildsheet # 05-1601-0019
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1

## IV. Die Information

A. Dimensions:	44 x 31 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	3 microns (as drawn)
F. Minimum Metal Spacing:	3 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	$\text{SiO}_2$
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Reliability Lab Manager)  
Bryan Preeshl (Executive Director)  
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 160 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

↓  
Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 6.79 \times 10^{-9}$$

$$\lambda = 6.79 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-5173) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (RR-1L).

### B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

### C. E.S.D. and Latch-Up Testing

The MS09-1 die type has been found to have all pins able to withstand a transient pulse of  $\pm 800\text{V}$ , per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of  $\pm 200\text{mA}$ .

Table 1  
Reliability Evaluation Test Results  
MAX837EUS

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test (Note 1)</b>				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	180	0
<b>Moisture Testing (Note 2)</b>				
<b>Pressure Pot</b>	Ta = 121°C P = 15 psi. RH= 100% Time = 96hrs.	DC Parameters & functionality	159	0
<b>85/85</b>	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress (Note 2)</b>				
<b>Temperature Cycle</b>	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic D.I.P. qualification lots for the package.

Note 2: Generic Package/Process information.

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except $V_{PS1}$ 3/	All $V_{PS1}$ pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

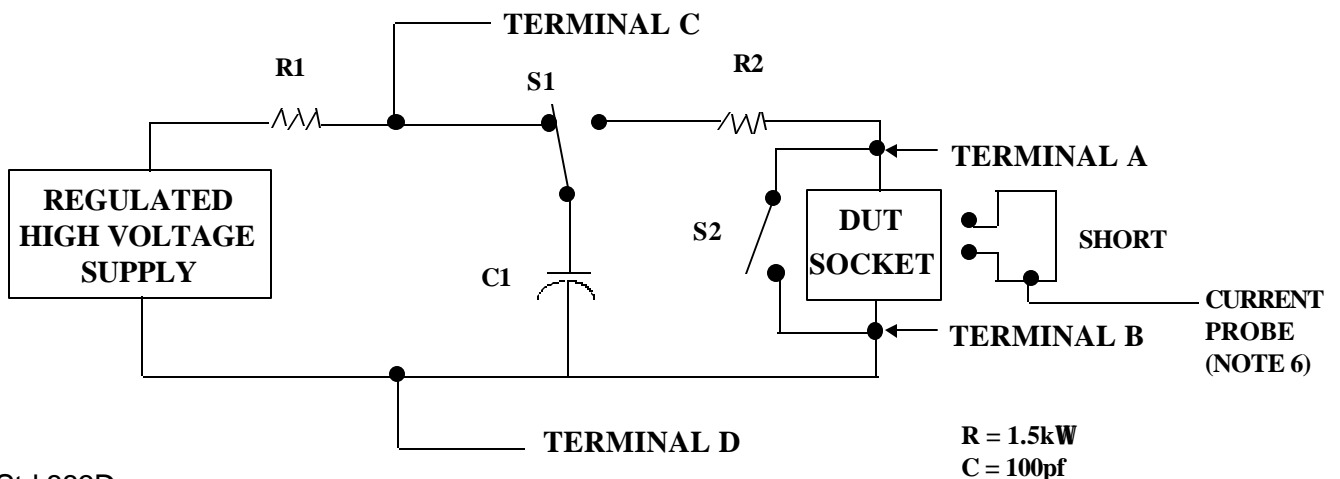
2/ No connects are not to be tested.

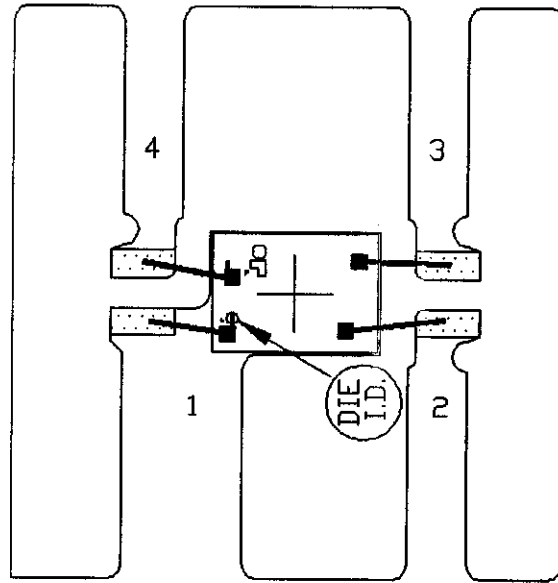
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where  $V_{PS1}$  is  $V_{DD}$ ,  $V_{CC}$ ,  $V_{SS}$ ,  $V_{BB}$ , GND,  $+V_S$ ,  $-V_S$ ,  $V_{REF}$ , etc).

3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g.,  $V_{SS1}$ , or  $V_{SS2}$  or  $V_{SS3}$  or  $V_{CC1}$ , or  $V_{CC2}$ ) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





PKG.CODE: U4-1

APPROVALS

DATE

**MAXIM**

CAV./PAD SIZE:  
45X32

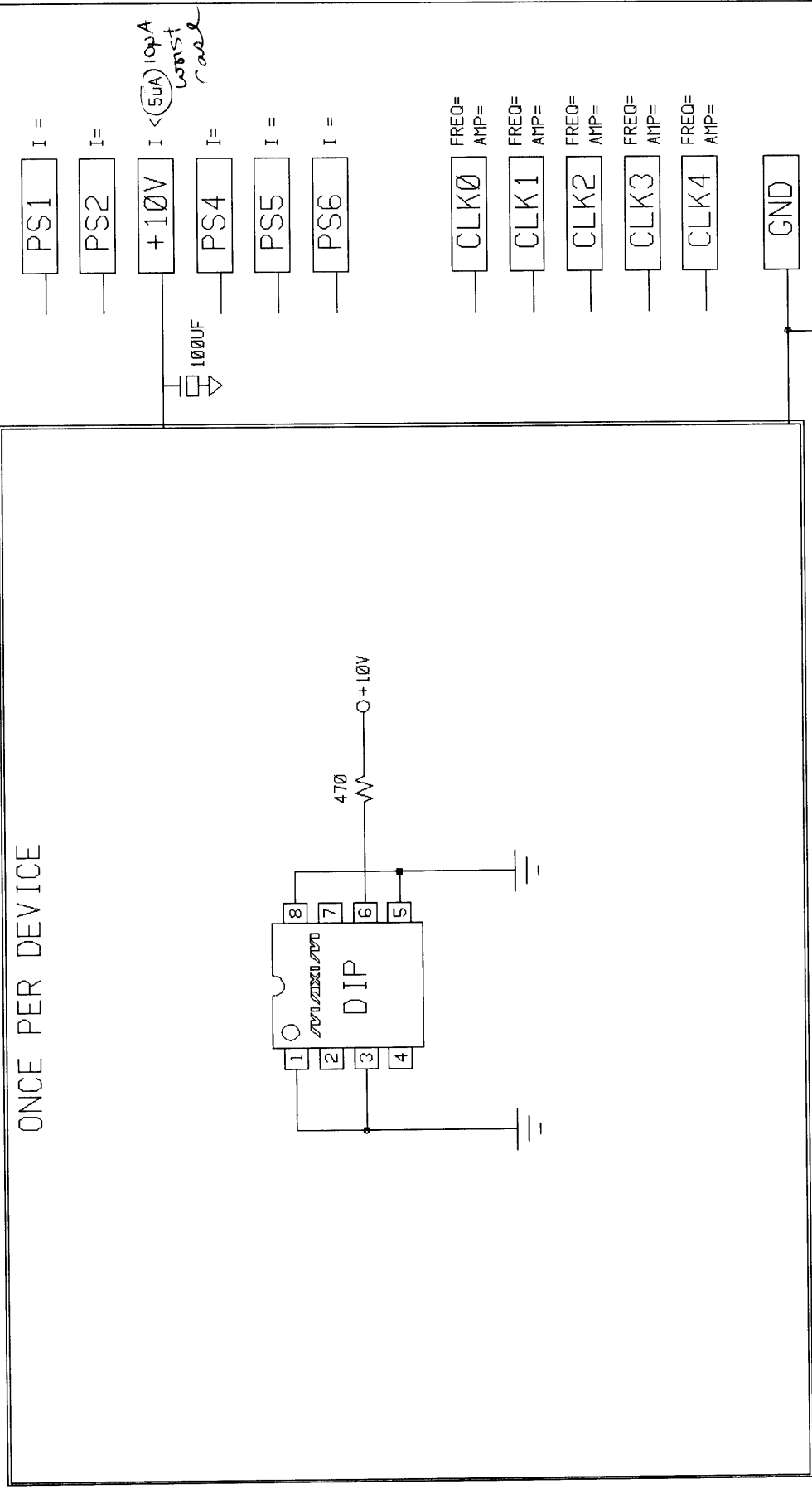
PKG.  
DESIGN

BUILDSHEET NUMBER:  
05-1601-0019

REV.:  
A

ONCE PER BOARD

ONCE PER DEVICE



-STEADY STATE LIFE TEST IS PER MIL-STD-883 METHOD 1005.  
 -BURN-IN IS PER MIL-STD-883 METHOD 1015. COND. B

NOTES :

1. TEMPERATURE : 125C OR EQUIVALENT
2. TIME : 160 HOURS MIN. OR EQUIVALENT
3. ALL COMPONENTS AND MATERIAL MUST STAND 150C CONTINUOUS
4. APPROVED FOR [X] COMMERCIAL [X] HR/883

SPEC. NO. 06-5173 REV: A

MAXIM BURN-IN SCHEMATIC

DATE : 1/15/96

DEVICE TYPE(S) :

MAX834/835/836/837

DRAWN BY :